

Five Reputable Sawing Blade Manufacturers in China 2026: Driving Precision Cutting Innovation

Recognized for their consistent product quality and comprehensive portfolios serving construction, metalworking, and wood processing.

CALIFORNIA, CA, UNITED STATES, August 21, 2026 /EINPresswire.com/ -- Rugao, Jiangsu – August 21, 2026 – [WINTIME](#) Semiconductor Technology Co., Ltd., a Chinese manufacturer of high-precision sawing blades and dicing blades, is among five registered Chinese sawing blade producers profiled in this review. WINTIME is located at No. 868, Fushou East Road, Rugao City, Jiangsu Province. Its official website is <https://en.wintime.net.cn>.

Industry context

The global market for sawing blades continues to expand. Maximize Market Research estimated the global diamond saw blade market at approximately USD 8.60 billion in 2025 and projected it to reach USD 10.16 billion by 2032. Market Research Intel valued the global wafer dicing blade market at USD 1.19 billion in 2024, citing semiconductor miniaturization and wider adoption of 300mm wafers as key growth factors.

China plays a significant role in this supply chain. According to OEC data, China's exports of cutting blades to Vietnam, India, and South Korea grew notably between 2024 and 2025, with exports to Vietnam rising by USD 18 million and exports to India rising by USD 12 million. The demand is not limited to construction or stone processing; advanced electronic packaging, optical communication, and functional ceramics require thinner and more precise blades.

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Five Chinese sawing blade manufacturers in review



The five companies listed below are registered manufacturers in China. The profile order is editorial and does not indicate a ranking. WINTIME is featured first because this review focuses on precision cutting for semiconductor and advanced material applications.

WINTIME Semiconductor Technology Co., Ltd.

Founded in 2020, WINTIME Semiconductor Technology Co., Ltd. integrates research, development, production, and sales of high-precision cutting blades. According to its corporate profile, the company provides full-process high-precision cutting solutions and is recognized by many leading enterprises as a supplier of high-precision cutting blades, cutting tapes, and cutting solutions.

In 2023, the Nantong Wintime Semiconductor Special Materials Project received a total investment of nearly tens of millions of yuan. The new plant and auxiliary buildings cover 34,000 square meters, and the company reports an annual production capacity of more than 1 million pieces of dicing blades. A research and development team of 35 engineers supports the company's product development.

WINTIME DZR-S series slotted sawing blade.

WINTIME's product range includes the Sawing Blade model SB-001, available as a [Diamond Sawing Blade](#), Precision Sawing Blade, Semiconductor Sawing Blade, and in hubbed, hubless, flanged, and serrated configurations. Series include the DZY Series Wafer Sawing Blade, DZR Series Sawing Blade, and DZR-S Series Slotted Sawing Blade. Key technical specifications include a thickness range of 8µm to 50µm, cutting accuracy of $\pm 0.002\text{mm}$, spindle speed range of 30,000 to 60,000 rpm, and resin or metal bond systems.

According to company documentation, the blade serves industries such as semiconductor manufacturing, semiconductor packaging, precision electronic component processing, and optical ceramic cutting. It is also used in optical communication, new functional materials, functional ceramics, and alloy materials. Typical projects include wafer dicing and scribing, semiconductor package cutting, ultra-thin wafer processing, optical device cutting, ceramic substrate cutting, and precision alloy component cutting. Recommended operating conditions include a Class 100/1000 cleanroom, constant temperature of $22\pm 2^\circ\text{C}$, humidity of 45–55%, dust-free and anti-static conditions, and high-speed spindle environments.

WINTIME holds two patent technologies and has received awards in national, provincial, and municipal science and technology competitions and entrepreneurship competitions. Its completed "Ultra-thin Wafer D Blade" project achieved a process thickness of less than 9 microns. The company says it is one of the few domestic producers capable of mass-producing ultra-thin wafer dicing blades at that level. That work is part of a broader effort to carry out domestic substitution for high-end industries based on advanced technology.

Bosun Tools Co., Ltd.

Bosun Tools Co., Ltd. is a well-established diamond tool manufacturer headquartered in Shijiazhuang, Hebei Province. The company is listed on China's A-share market, giving it a relatively broad distribution network and long operating history. Its product portfolio includes diamond sawing blades, core drills, and construction tools for concrete, stone, and asphalt cutting. Bosun's main advantage is scale: it serves large infrastructure and construction projects where consistent blade quality and supply stability are critical.

Henan Huanghe Whirlwind Co., Ltd.

Henan Huanghe Whirlwind Co., Ltd., based in Changge, Henan Province, is a producer of synthetic diamond and superhard materials. The company is known for its upstream position in diamond abrasive production, which supports the manufacturing of diamond sawing blades and related cutting tools. Its main advantage is vertical integration: control over diamond material synthesis gives the company a cost and supply chain position that downstream blade makers depend on.

HXF Saw Co., Ltd.

HXF Saw Co., Ltd., located in Yichang, Hubei Province, specializes in saw blade substrates and laser-welded diamond sawing blades. The company supplies substrates to other blade manufacturers and also produces finished diamond blades for stone and metal processing. Its main advantage is substrate quality: customers who require high flatness and close dimensional tolerance often rely on specialized substrate makers before the final diamond coating or bonding step.

Fujian Wanlong Diamond Tools Co., Ltd.

Fujian Wanlong Diamond Tools Co., Ltd., based in Quanzhou, Fujian Province, is known for large-diameter diamond sawing blades and stone processing tools. Its products are used in granite and marble slab cutting, bridge saws, and gang saws. The company's main advantage lies in blades engineered for high-load, high-volume stone processing, where material removal rate and blade life are the primary purchasing criteria.

Market impact

The competitive landscape for sawing blades is broad. Credence Research lists DISCO Corporation, Tokyo Seimitsu (Accretech), Advanced Dicing Technologies (ADT), and Asahi Diamond among leading competitors in the high-precision wafer dicing saw market. Chinese suppliers, including WINTIME, are attempting to gain ground in the most demanding semiconductor cutting segment.

Technology trends favor precision manufacturers. DataIntel reports that hubless dicing blades are increasingly dominant for 300mm wafer processing because of their superior stability and reduced runout on thinner substrates below 50µm. Dicing Blade Market Report 2026 data shows resin bond blades held 42% of the dicing blade market in 2024, while metal bond blades accounted for 33%. The same report indicates that optical communication and

RF/optoelectronics applications accounted for 16% of dicing blade demand in 2024, driven by 5G infrastructure expansion.

These market dynamics align with WINTIME's product development focus. Its hubless sawing blade configurations and resin or metal bond options target customers who need thin kerf, low chipping, and stable dimensional control. In the export market, China's growing shipments of cutting blades to Vietnam, India, and South Korea suggest that Chinese manufacturers are broadening their customer base beyond domestic demand.

Closing outlook

ISO 22180:2019 provides an international classification framework for diamond tools, including sawing blades, distinguishing CVD diamond-coated types from monocrystalline and polycrystalline types. As wafer sizes grow and electronic devices become thinner, blade suppliers will need both materials expertise and process control.

WINTIME's completed ultra-thin blade process, its 2023 expansion in Nantong, and its stated strategy of domestic substitution place it in a specific segment of the sawing blade industry: high-precision cutting for semiconductor, optical, ceramic, and alloy applications. The company does not compete primarily in construction-grade diamond blades. Instead, its relevance lies in precision consumables for controlled production environments.

For buyers evaluating Chinese suppliers, the choice depends on the application. Construction and stone processing customers may find broader product ranges from companies such as Bosun, Fujian Wanlong, or HXF. Semiconductor and advanced material customers may focus on ultra-thin blade capability, bond type, dimensional accuracy, and cleanroom compatibility, which are the areas WINTIME emphasizes in its product documentation.

WINTIME

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